

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSC0906NS	**Issued**	27. April 2022
MA#	MA005738946		
Package	PG-TDSON-8-51	**Weight***	99.99 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.224	0.22	0.22	2245	2245
leadframe	inorganic material	phosphorus	7723-14-0	0.014	0.01		136	
	non noble metal	zinc	7440-66-6	0.055	0.05		545	
	non noble metal	iron	7439-89-6	1.090	1.09		10904	
	non noble metal	copper	7440-50-8	44.271	44.29	45.44	442766	454351
wire	noble metal	gold	7440-57-5	0.032	0.03	0.03	324	324
encapsulation	organic material	carbon black	1333-86-4	0.086	0.09		863	
	plastics	epoxy resin	-	6.816	6.82		68171	
	inorganic material	silicondioxide	60676-86-0	36.238	36.24	43.15	362427	431461
leadfinish	non noble metal	tin	7440-31-5	1.264	1.26	1.26	12639	12639
plating	noble metal	silver	7440-22-4	0.029	0.03	0.03	290	290
solder	noble metal	silver	7440-22-4	0.009	0.01		94	
	non noble metal	tin	7440-31-5	0.019	0.02		188	
	non noble metal	lead	7439-92-1	0.348	0.35	0.38	3476	3758
heat sink clip	inorganic material	phosphorus	7723-14-0	0.003			28	
	non noble metal	zinc	7440-66-6	0.011	0.01		114	
	non noble metal	iron	7439-89-6	0.228	0.23		2278	
	non noble metal	copper	7440-50-8	9.250	9.25	9.49	92512	94932
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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